

L Number	Hits	Search Text	DB	Time stamp
-	926	257/685	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/05/22 11:17
-	2074	257/686	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/05/22 11:17
-	4631	257/666	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/05/22 13:24
-	2235	257/690	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/05/22 11:17
-	2469	257/692	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/05/22 11:17
-	1660	257/701	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/05/22 11:17
-	4044	257/787	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/05/22 11:17
-	13245	257/685 257/686 257/666 257/690 257/692 257/701 257/787	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/05/22 11:18
-	3253	((257/685 257/686 257/666 257/690 257/692 257/701 257/787) and lead and (chip die IC (integrated near circuit)) and (encapsulant encapsulating encapsulate mold))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/05/22 12:19
-	965	((257/685 257/686 257/666 257/690 257/692 257/701 257/787) and lead and (chip die IC (integrated near circuit)) and (encapsulant encapsulating encapsulate mold)) and ((I/O bond input/output) near pad)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/05/22 11:22
-	27	((257/685 257/686 257/666 257/690 257/692 257/701 257/787) and lead and (chip die IC (integrated near circuit)) and (encapsulant encapsulating encapsulate mold)) and (lead near recess\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/05/22 13:22
-	26	257/666 and (lead near recess\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/05/22 13:22
-	9	(257/666 and (lead near recess\$3)) not (((257/685 257/686 257/666 257/690 257/692 257/701 257/787) and lead and (chip die IC (integrated near circuit)) and (encapsulant encapsulating encapsulate mold)) and (lead near recess\$3))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/05/22 13:22
-	1450	257/666 and chip and (encapsulant encapsulating encapsulate mold)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/05/22 15:04
-	1019	(257/666 and chip and (encapsulant encapsulating encapsulate mold)) not (((257/685 257/686 257/666 257/690 257/692 257/701 257/787) and lead and (chip die IC (integrated near circuit)) and (encapsulant encapsulating encapsulate mold)) and ((I/O bond input/output) near pad))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/05/22 15:04

-	781	((257/666 and chip and (encapsulant encapsulating encapsulate mold)) not (((257/685 257/686 257/666 257/690 257/692 257/701 257/787) and lead and (chip die IC (integrated near circuit)) and (encapsulant encapsulating encapsulate mold)) and ((I/O bond input/output) near pad))) and pad	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/05/22 15:05
-	294	((metal conductive conducting conductor) near lead) and chip and ((I/O input/output) near pad)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/06/05 15:26
-	1872	lead and chip and ((I/O input/output) near pad)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/06/05 13:38
-	668	(lead and chip and ((I/O input/output) near pad)) and 257/\$6.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/06/05 15:28
-	505	((lead and chip and ((I/O input/output) near pad)) and 257/\$6.ccls.) not ((metal conductive conducting conductor) near lead) and chip and ((I/O input/output) near pad))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/06/05 13:39
-	294	((metal conductive conducting conductor) near lead) and chip and ((I/O input/output bond) near pad)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/06/05 15:28
-	1346	((metal conductive conducting conductor) near lead) and chip and ((I/O input/output bond) near pad)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/06/05 15:28
-	1052	((metal conductive conducting conductor) near lead) and chip and ((I/O input/output bond) near pad)) not ((metal conductive conducting conductor) near lead) and chip and ((I/O input/output) near pad))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/06/05 15:28
-	516	((metal conductive conducting conductor) near lead) and chip and ((I/O input/output bond) near pad)) not ((metal conductive conducting conductor) near lead) and chip and ((I/O input/output) near pad))) and 257/\$6.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/06/05 15:29
-	516	((metal conductive conducting conductor) near lead) and chip and ((I/O input/output bond) near pad)) not ((metal conductive conducting conductor) near lead) and chip and ((I/O input/output) near pad))) and 257/\$6.ccls.) not ((lead and chip and ((I/O input/output) near pad)) and 257/\$6.ccls.) not ((metal conductive conducting conductor) near lead) and chip and ((I/O input/output) near pad)))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/06/05 15:29